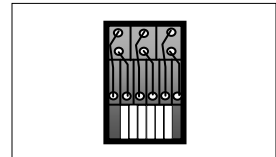
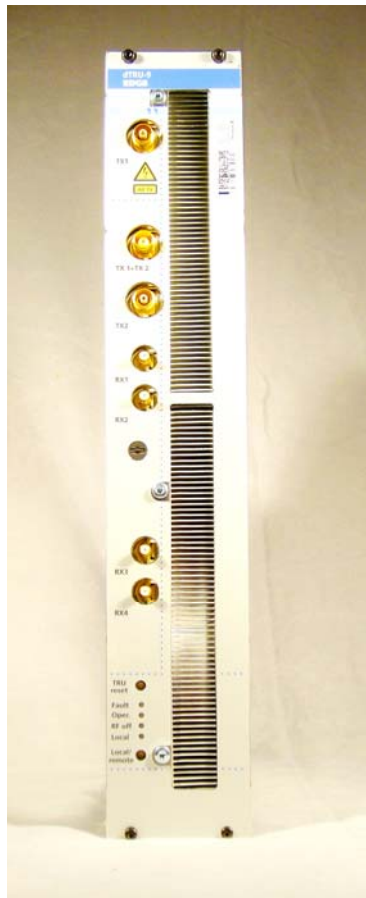


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Ericsson dTRU GSM/EDGE 900MHz Model KRC 131 1002/2 R5F

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